



## Product Change Notification - LIAL-10JYTJ941

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**Date:**

06 Mar 2020

**Product Category:**

Driver / Interface ICs

**Affected CPNs:****Notification subject:**

CCB 3921 Final Notice: Qualification of NSEB as a new assembly site for selected HV5523 and HV5623 device families available in 44L WQFN (7x7x0.8mm) package using Au wire.

**Notification text:****PCN Status:**

Final notification.

**PCN Type:**

Manufacturing Change

**Microchip Parts Affected:**

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:**

Qualification of NSEB as a new assembly site for selected HV5523 and HV5623 device families available in 44L WQFN (7x7x0.8mm) package using Au wire.

**Pre Change:**

Assembled at CARC using QMI519 die attach, EME-G770HCD mold compound and A194 lead frame material

**Post Change:**

Assembled at NSEB using 8600 die attach, G700LTD mold compound and EFTEC-64T lead frame material.

**Pre and Post Change Summary:**

	Pre Change	Post Change
Assembly Site	Carsem (Suzhou) (CARC)	UTAC Thai Limited (UTL-1) LTD. (NSEB)
Wire material	Au	Au
Die attach material	QMI519	8600
Molding compound material	EME-G770HCD	G700LTD
Lead frame material	A194	EFTEC-64T
MSL Classification	MSL 3	MSL 1

**Impacts to Data Sheet:**

None

**Change Impact:**

None

**Reason for Change:**

To improve manufacturability by qualifying NSEB as a new assembly site.

**Change Implementation Status:**

In Progress

**Estimated First Ship Date:**

April 06, 2020 (date code: 2015)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts..

**Time Table Summary:**

	September 2019					-->	March 2020					April 2020			
Workweek	36	37	38	39	40		10	11	12	13	14	15	16	17	18
Initial PCN Issue Date				X											
Qual Report Availability							X								
Final PCN Issue Date							X								
Estimated Implementation Date												X			

**Method to Identify Change:**

Traceability code.

**Qualification Report:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual Report.

**Revision History:**

**September 25, 2019:** Issued initial notification.

**March 06, 2020:** Issued final notification. Attached the qualification report. Provided estimated first ship date to be on April 06, 2020.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachment(s):**

[PCN\\_LIAL-10JYTJ941\\_Qual\\_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN)

HV5523K7-G

HV5523K7-G-M933

HV5623K7-G

HV5623K7-G-M933